

ABSTRACT OF THE DISCLOSURE

A process for machining a wafer-like workpiece between two plates, in which material is abraded from the workpiece under the influence of an auxiliary substance supplied and of ^{28.05.03 HZ} ~~pressure~~ ^{28.05.03 Dm} ~~a weight~~ ^{Pressure} acting on the workpiece. In this process, the ~~load~~ on the workpiece ~~from the weight~~ is significantly reduced and ^{28.05.03 Dm} ~~28.05.03 HZ~~ then increased again at least once during the machining of the workpiece, and the supply of the auxiliary substance is reduced as the ^{pressure} ~~weight~~ is increased. ^{28.05.03 Dm} ~~28.05.03 HZ~~